

In the Claims

1. (amended) A system for removing a contaminant layer from a surface of a semiconductor process component, the system comprising:
 - a. a receptacle receiving the semiconductor process component and a first volume of [[liquid]] an acid solution, the acid solution [[liquid]] selected to remove the contaminant layer from the semiconductor process component; and
 - b. at least one liquid-displacing element immersed in the acid solution [[liquid]], the at least one liquid-displacing element displacing a second volume greater than half the first volume.
2. (original) The system of claim 1, wherein the at least one liquid-displacing element includes a plurality of liquid-displacing elements.
3. (amended) The system of claim 2, wherein the liquid-displacing element moves freely within the [[liquid]] acid solution.
4. (original) The system of claim 2, wherein the plurality of liquid-displacing elements are spherical.
5. (original) The system of claim 2, wherein ones of the plurality of liquid-displacing elements are of different sizes.
6. (original) The system of claim 2, wherein the displacement elements number at least one hundred.

7. (original) The system of claim 1, wherein the component displaces a component volume less than the second volume.
8. (amended) ~~The system of claim 2,~~ A system for removing a contaminant layer from a surface of a semiconductor process component, the system comprising:
 - a. a receptacle receiving the component and a first volume of liquid, the liquid selected to remove the contaminant layer; and
 - b. at least one liquid-displacing element immersed in the liquid, the at least one liquid-displacing element displacing a second volume greater than half the first volume;
 - c. wherein the at least one liquid-displacing element includes a plurality of liquid-displacing elements; and
 - d. wherein the at least one liquid-displacing element defines a cavity receiving the component.
9. (original) The system of claim 8, wherein the component is of a shape, and wherein the cavity matches the shape.
10. (original) The system of claim 1, further comprising a support, wherein the component is suspended by the support.
11. (amended) The system of claim 10, wherein the support includes a pommel adapted to cover the receptacle.
12. (amended) The system of claim 1, wherein the [[liquid]] solution is of a first density and the liquid-displacing element is of a second density is greater than the first density.

13. (amended) ~~The system of claim 1, further comprising A~~
system for removing a contaminant layer from a surface of a
semiconductor process component, the system comprising:
a. a receptacle receiving the component and a first
volume of liquid, the liquid selected to remove the
contaminant layer; and
b. at least one liquid-displacing element immersed in the
liquid, the at least one liquid-displacing element
displacing a second volume greater than half the first
volume; and
c. a cleaning bench receiving the receptacle.
14. (original) The system of claim 13, wherein the cleaning bench includes a secondary containment vessel for the liquid.
15. (original) The system of claim 13, wherein the receptacle is keyed to fit the cleaning bench.
16. (original) The system of claim 13, further comprising a second receptacle.
17. (original) The system of claim 13, wherein the receptacle includes a first inlet connector and the bench includes a second inlet connector mating with the first inlet connector, the first and second inlet connectors passing the liquid from the bench to the receptacle.
18. (original) The system of claim 17, wherein removing the receptacle from the bench disconnects the first inlet connector from the second inlet connector.
19. (original) The system of claim 17, wherein the receptacle

includes a first drain connector and the bench includes a second drain connector mating with the first drain connector, the first and second drain connectors passing the liquid from the receptacle to the bench.

20. (original) The system of claim 1, wherein the at least one liquid-displacing element is of a material that will not react with the liquid.
21. (new) The system of claim 16, wherein the second receptacle is adapted to receive a second component differently shaped than the first component and a second volume of liquid, the system further comprising at least one second liquid-displacing element shaped to receive the second component.
22. (new) A cleaning bench comprising:
 - a. a first receptacle receiving a first component of a first component shape and a first volume of liquid, the liquid selected to remove a first contaminant layer from the first component, the first receptacle having a first receptacle shape similar to at least a portion of the first component shape; and
 - b. a second receptacle receiving a second component of a second component shape and a second volume of liquid, the liquid selected to remove a second contaminant layer from the second component, the first receptacle having a second receptacle shape similar to at least a portion of the second component shape.
23. (new) The cleaning bench of claim 22, wherein the first and second component shapes are different.
24. (new) The cleaning bench of claim 22, wherein each of the

first and second receptacles includes a respective mark identifying the respective first and second components.

25. (new) The cleaning bench of claim 22, further comprising a handle supporting the first component in the first chamber, the handle including a pommel adapted to cover the first chamber.
26. (new) The cleaning bench of claim 22, wherein the first chamber is textured to allow the first liquid to access to the surface of the first component.